PS2806-1,PS2806-4

R08DS0176EJ0101
Rev.1.01
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HIGH ISOLATION VOLTAGE AC INPUT, DARLINGTON TRANSISTOR TYPE SSOP PHOTOCOUPLER

DESCRIPTION

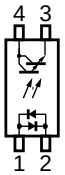
The PS2806-1 and PS2806-4 are optically coupled isolators containing a GaAs light emitting diode and an NPN silicon Darlington-connected phototransistor in a plastic SSOP for high density applications. This package has shield effect to cut off ambient light.

FEATURES

- High isolation voltage (BV = 2 500 Vr.m.s.)
- Small and thin package (4, 16-pin SSOP, Pin pitch 1.27 mm)
- AC input response
- High current transfer ratio (CTR = 2 000 % TYP. @ IF = ±1 mA, V_{CE} = 2 V)
- Ordering number of tape product: PS2806-1-F3, PS2806-4-F3
- Pb-free product
- Safety standards
  - UL approved: UL1577, Single protection
  - CSA approved: CAN/CSA-C22.2 No. 62368-1, Basic insulation
  - BSI approved: BS EN 62368-1, Basic/Supplementary insulation
  - VDE approved: DIN EN 60747-5-5 (Option)

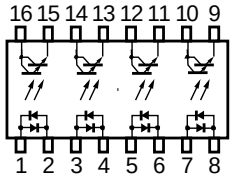
PIN CONNECTION
(Top View)

PS2806-1



1. Anode, Cathode
2. Cathode, Anode
3. Emitter
4. Collector

PS2806-4

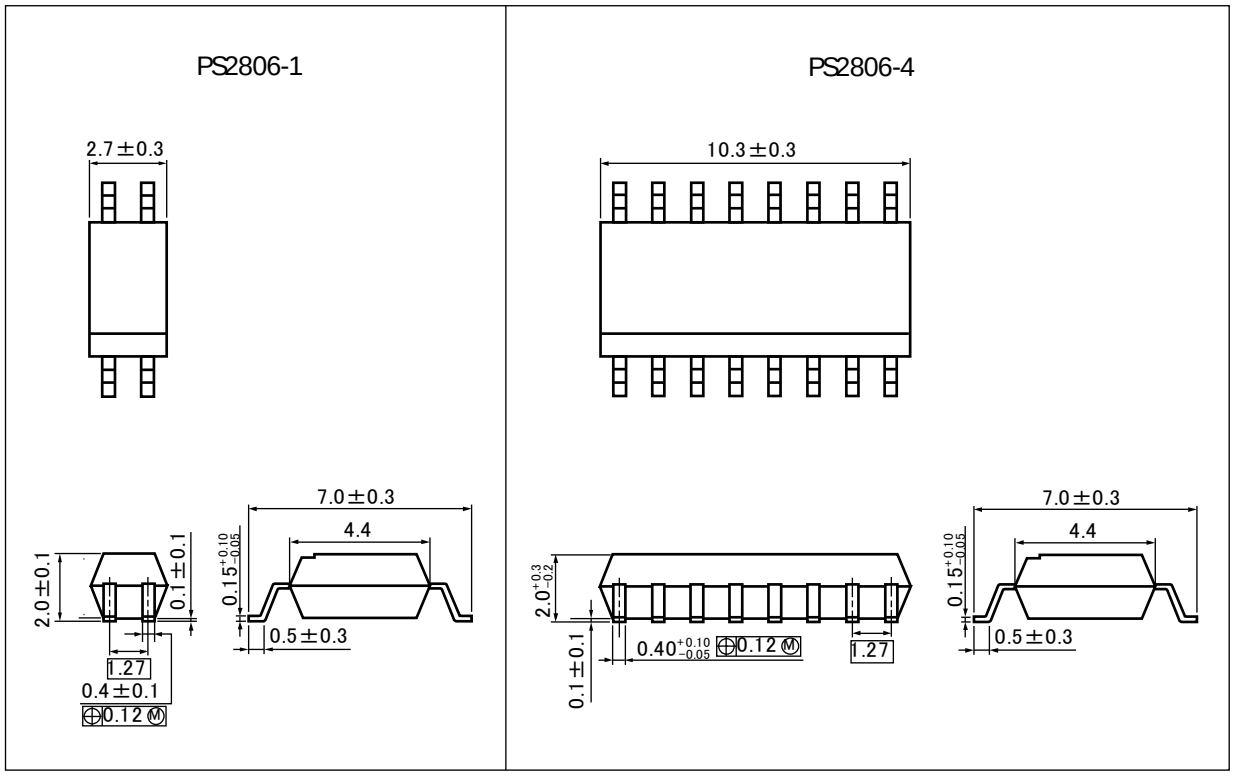


1. 3. 5. 7. Anode, Cathode
2. 4. 6. 8. Cathode, Anode
9. 11. 13. 15. Emitter
10. 12. 14. 16. Collector

APPLICATIONS

- Programmable logic controllers
- Measuring instruments
- Power supply
- Hybrid IC

PACKAGE DIMENSIONS (UNIT: mm)



Weight (4-pin SSOP) : 0.05 g (TYP.)

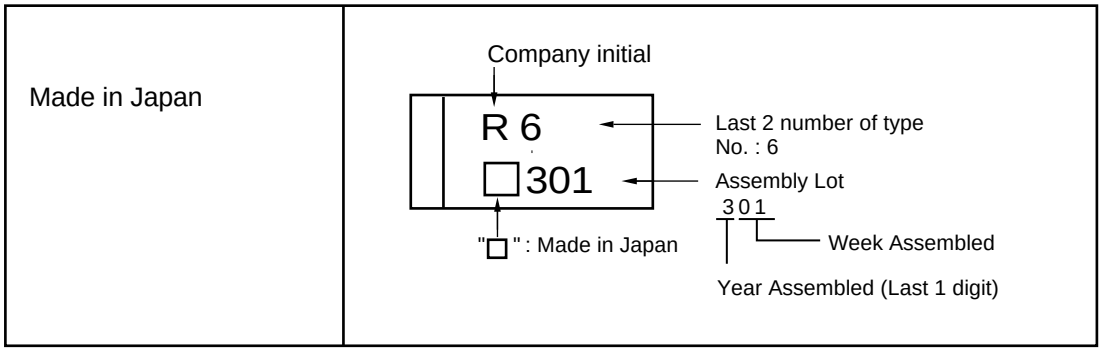
Weight (16-pin SSOP) : 0.2 g (TYP.)

PHOTOCOUPLER CONSTRUCTION

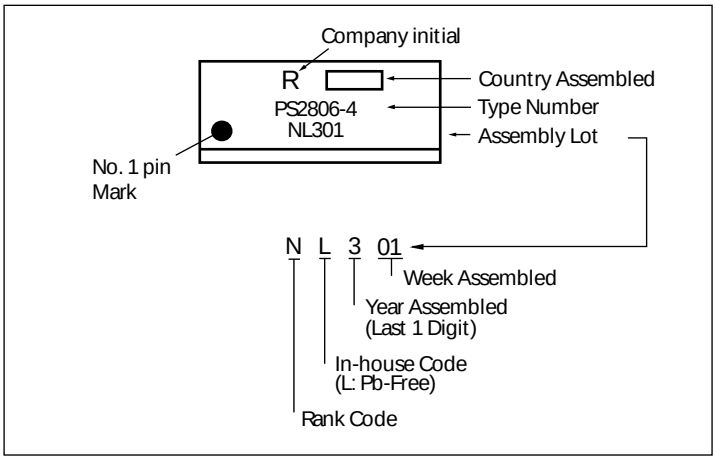
Parameter	MIN.
Air Distance	4.5 mm
Creepage Distance	4.5 mm
Isolation Thickness	0.1 mm

MARKING EXAMPLE

PS2806-1



PS2806-4



ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number*1
PS2806-1	PS2806-1-A	Pb-Free	Embossed Tape 50 pcs	Standard Products (UL, BSI, CSA Approved)	PS2806-1
PS2806-1-F3	PS2806-1-F3-A		Embossed Tape 3 500 pcs/reel		
PS2806-4	PS2806-4-A		Embossed Tape 10 pcs		PS2806-4
PS2806-4-F3	PS2806-4-F3-A		Embossed Tape 2 500 pcs/reel		
PS2806-1-V	PS2806-1-V-A		Embossed Tape 50 pcs	UL, BSI, CSA, DIN EN 60747-5-5 Approved	PS2806-1
PS2806-1-V-F3	PS2806-1-V-F3-A		Embossed Tape 3 500 pcs/reel		
PS2806-4-V	PS2806-4-V-A		Embossed Tape 10 pcs		PS2806-4
PS2806-4-V-F3	PS2806-4-V-F3-A		Embossed Tape 2 500 pcs/reel		

Notes: *1. For the application of the safety standard, the following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise specified)

Parameter		Symbol	Ratings		Unit
			PS2806-1	PS2806-4	
Diode	Forward Current (DC)	I_F	±50		mA/ch
	Power Dissipation Derating	ΔP_D/°C	0.6	0.8	mW/°C
	Power Dissipation	P_D	60	80	mW/ch
	Peak Forward Current *1	I_{FP}	±1		A/ch
Transistor	Collector to Emitter Voltage	V_{CEO}	40		V
	Emitter to Collector Voltage	V_{ECO}	6		V
	Collector Current	I_C	90	100	mA/ch
	Power Dissipation Derating	ΔP_C/°C	1.2		mW/°C
	Power Dissipation	P_C	120		mW/ch
Isolation Voltage *2		BV	2 500		Vr.m.s.
Operating Ambient Temperature		T_A	−55 to +100		°C
Storage Temperature		T_{stg}	−55 to +150		°C

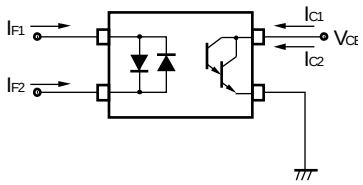
Notes: *1. PW = 100 µs, Duty Cycle = 1 %

*2. AC voltage for 1 minute at T_A = 25 °C, RH = 60 % between input and output.
Pins 1-2 shorted together, 3-4 shorted together (PS2806-1).
Pins 1-8 shorted together, 9-16 shorted together (PS2806-4).

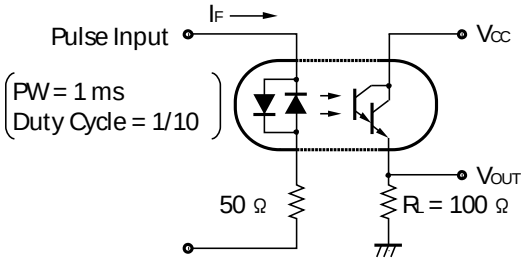
ELECTRICAL CHARACTERISTICS (T_A = 25 °C)

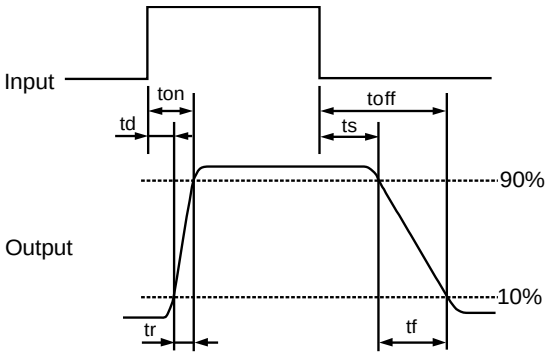
Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V_F	I_F = ±5 mA		1.1	1.4	V
	Terminal Capacitance	C_t	V = 0 V, f = 1.0 MHz		30		pF
Transistor	Collector to Emitter Dark Current	I_{CEO}	V_{CE} = 40 V, I_F = 0 mA			400	nA
Coupled	Current Transfer Ratio (I_C/I_F)	CTR	I_F = ±1 mA, V_{CE} = 2 V	200	2 000		%
	CTR Ratio *1	CTR1/ CTR2	I_F = 1 mA, V_{CE} = 2 V	0.3	1.0	3.0	
	Collector Saturation Voltage	$V_{CE(sat)}$	I_F = ±1 mA, I_C = 2 mA			1.0	V
	Isolation Resistance	R_{I-O}	V_{I-O} = 1.0 kV_{DC}	10^{11}			Ω
	Isolation Capacitance	C_{I-O}	V = 0 V, f = 1.0 MHz		0.4		pF
	Rise Time *2	t_r	V_{CC} = 5 V, I_C = 2 mA, R_L = 100 Ω		200		µs
	Fall Time *2	t_f			200		

Notes: *1. CTR1 = I_{C1}/I_{F1}, CTR2 = I_{C2}/I_{F2}



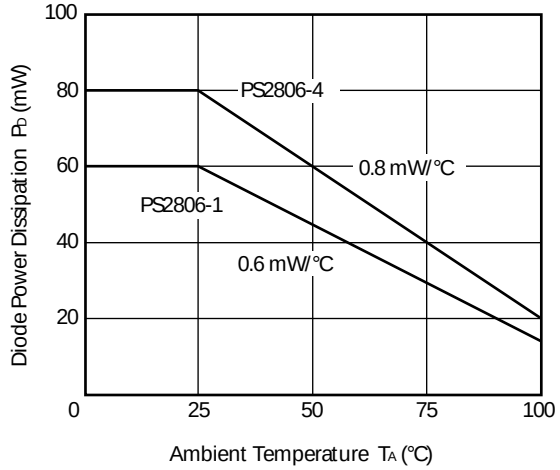
*2. Test circuit for switching time



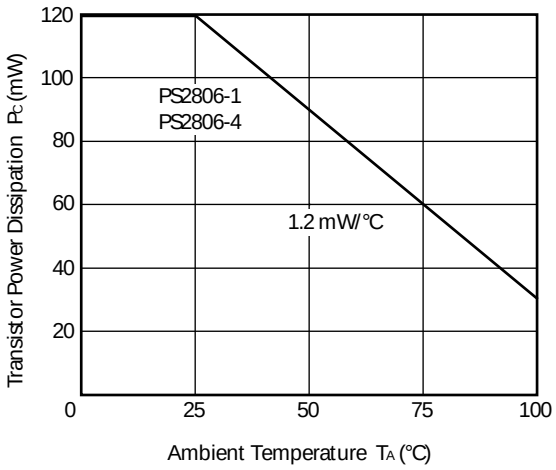


TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise specified)

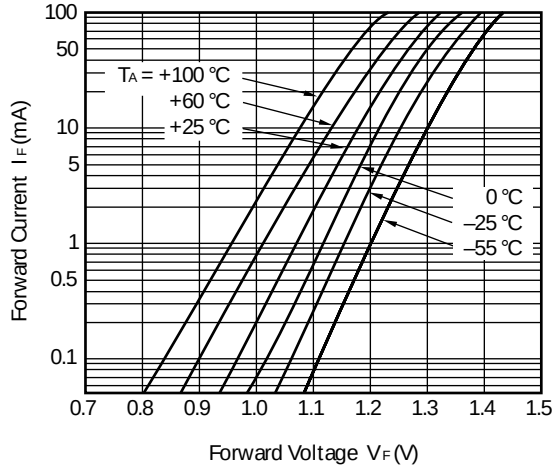
DIODE POWER DISSIPATION vs. AMBIENT TEMPERATURE



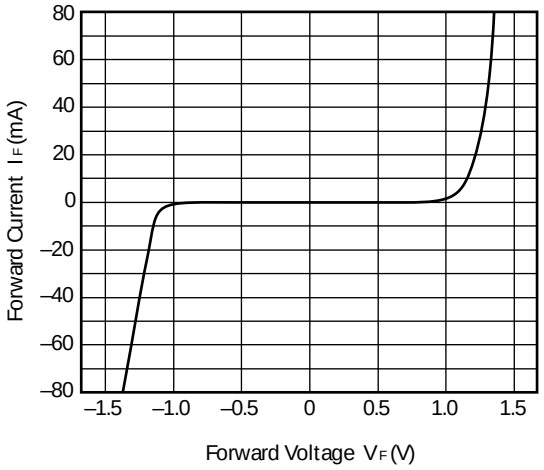
TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



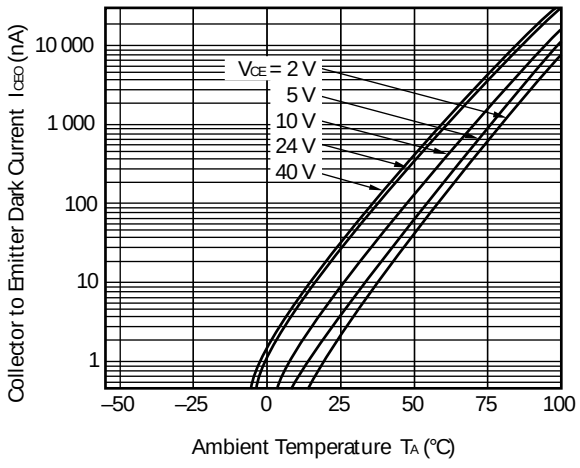
FORWARD CURRENT vs. FORWARD VOLTAGE



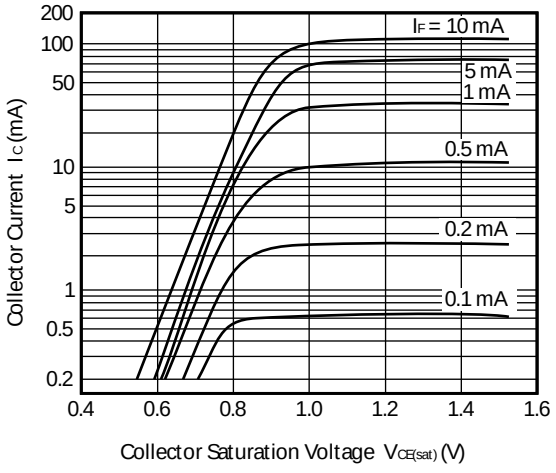
FORWARD CURRENT vs. FORWARD VOLTAGE



COLLECTOR TO EMITTER DARK CURRENT vs. AMBIENT TEMPERATURE

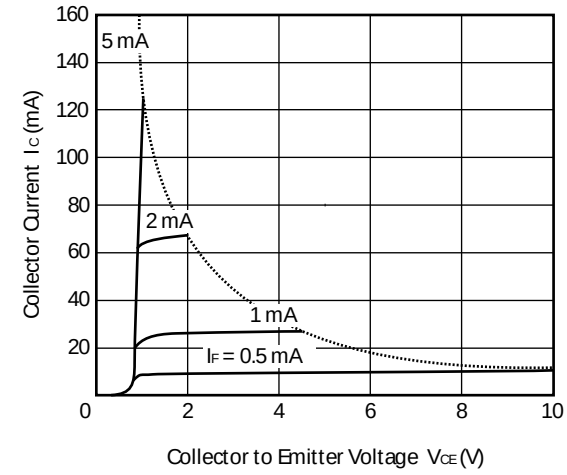


COLLECTOR CURRENT vs. COLLECTOR SATURATION VOLTAGE

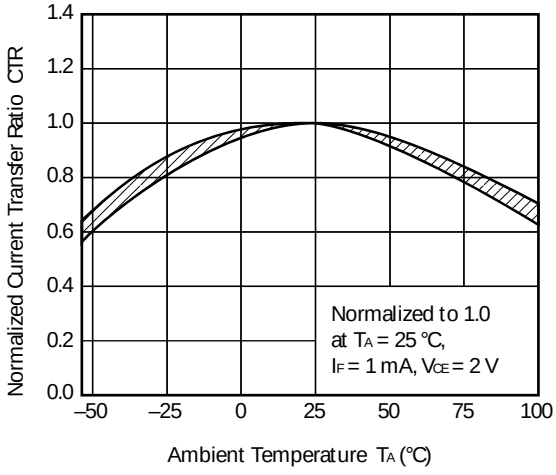


Remark The graphs indicate nominal characteristics.

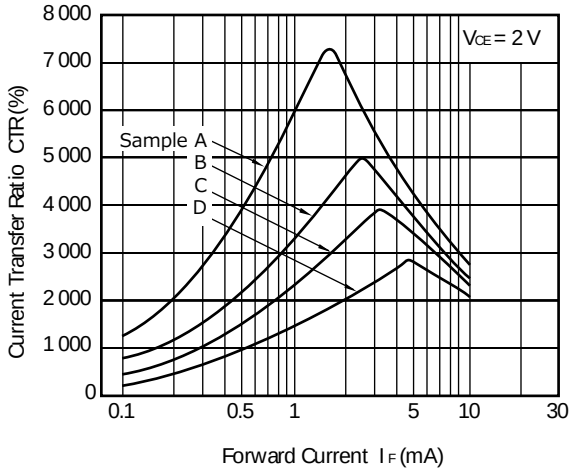
COLLECTOR CURRENT vs.
COLLECTOR TO EMITTER VOLTAGE



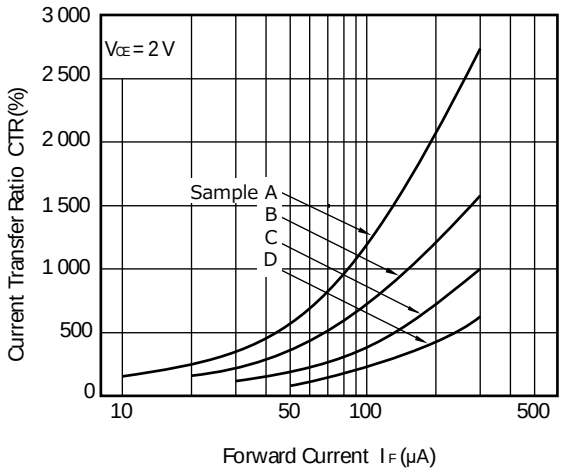
NORMALIZED CURRENT TRANSFER
RATIO vs. AMBIENT TEMPERATURE



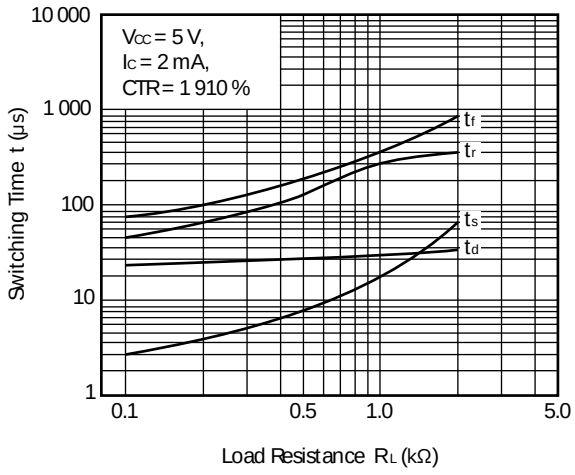
CURRENT TRANSFER RATIO vs.
FORWARD CURRENT



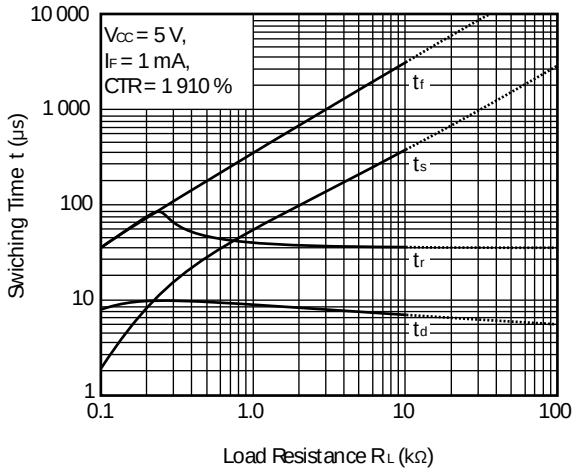
CURRENT TRANSFER RATIO vs.
FORWARD CURRENT



SWITCHING TIME vs.
LOAD RESISTANCE



SWITCHING TIME vs.
LOAD RESISTANCE

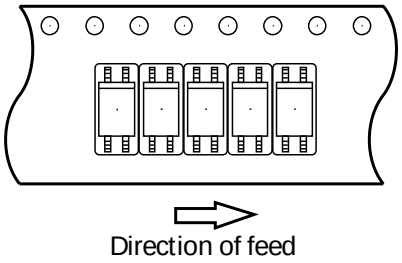


Remark The graphs indicate nominal characteristics.

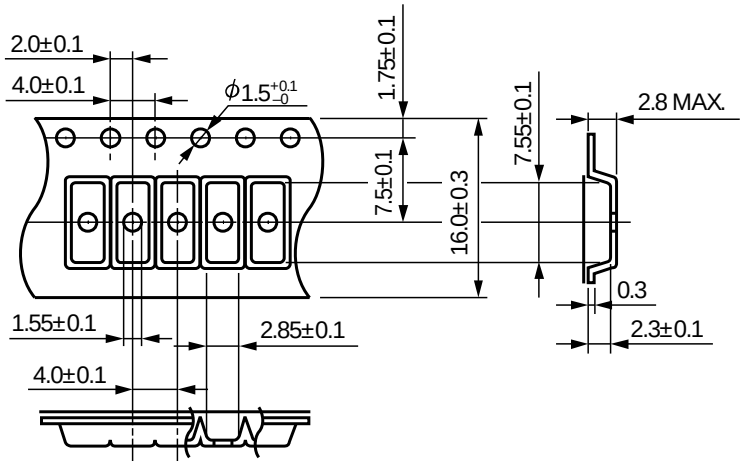
TAPING SPECIFICATIONS (UNIT: mm)

Tape Direction

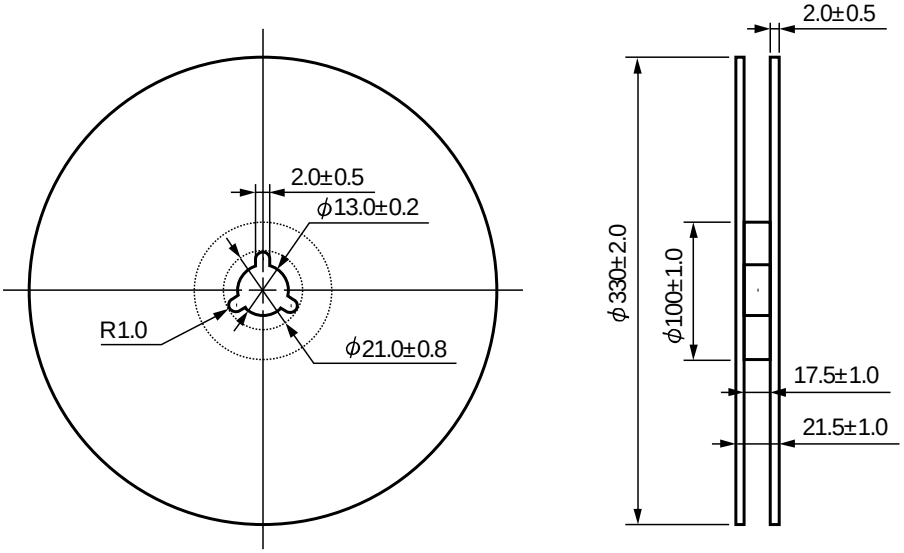
PS2806-1-F3



Outline and Dimensions (Tape)



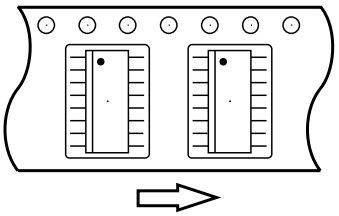
Outline and Dimensions (Reel)



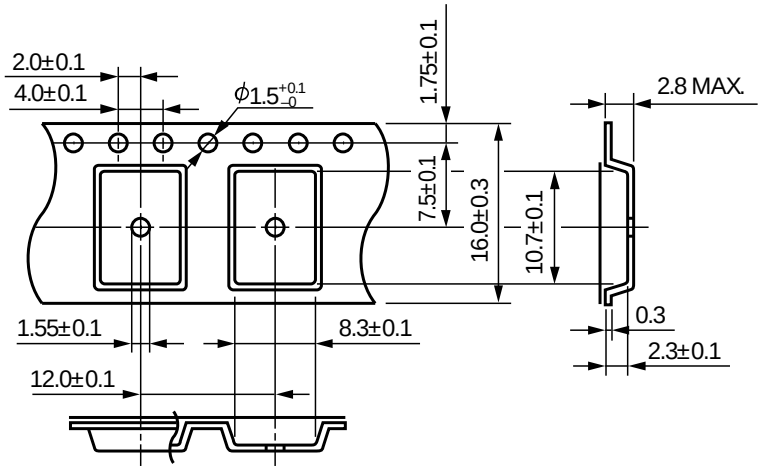
Packing: 3 500 pcs/reel

Tape Direction

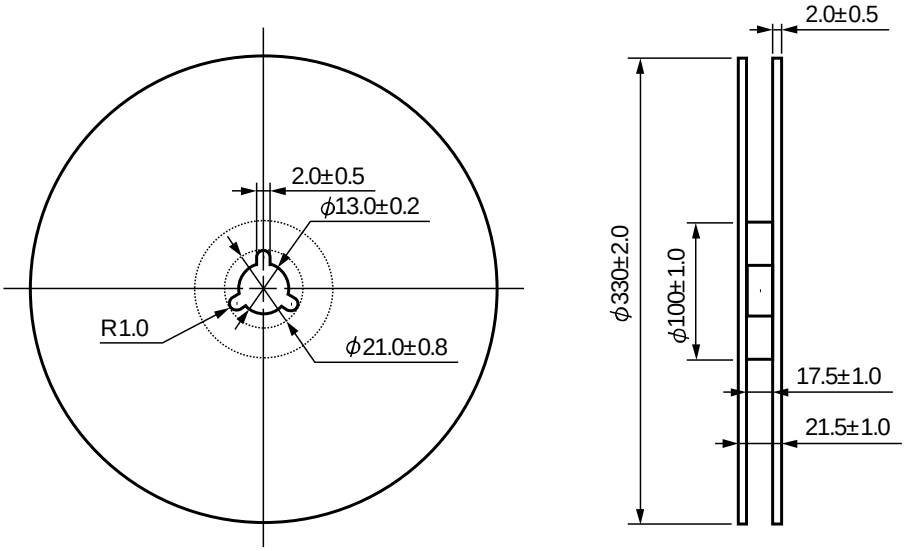
PS2806-4-F3



Outline and Dimensions (Tape)

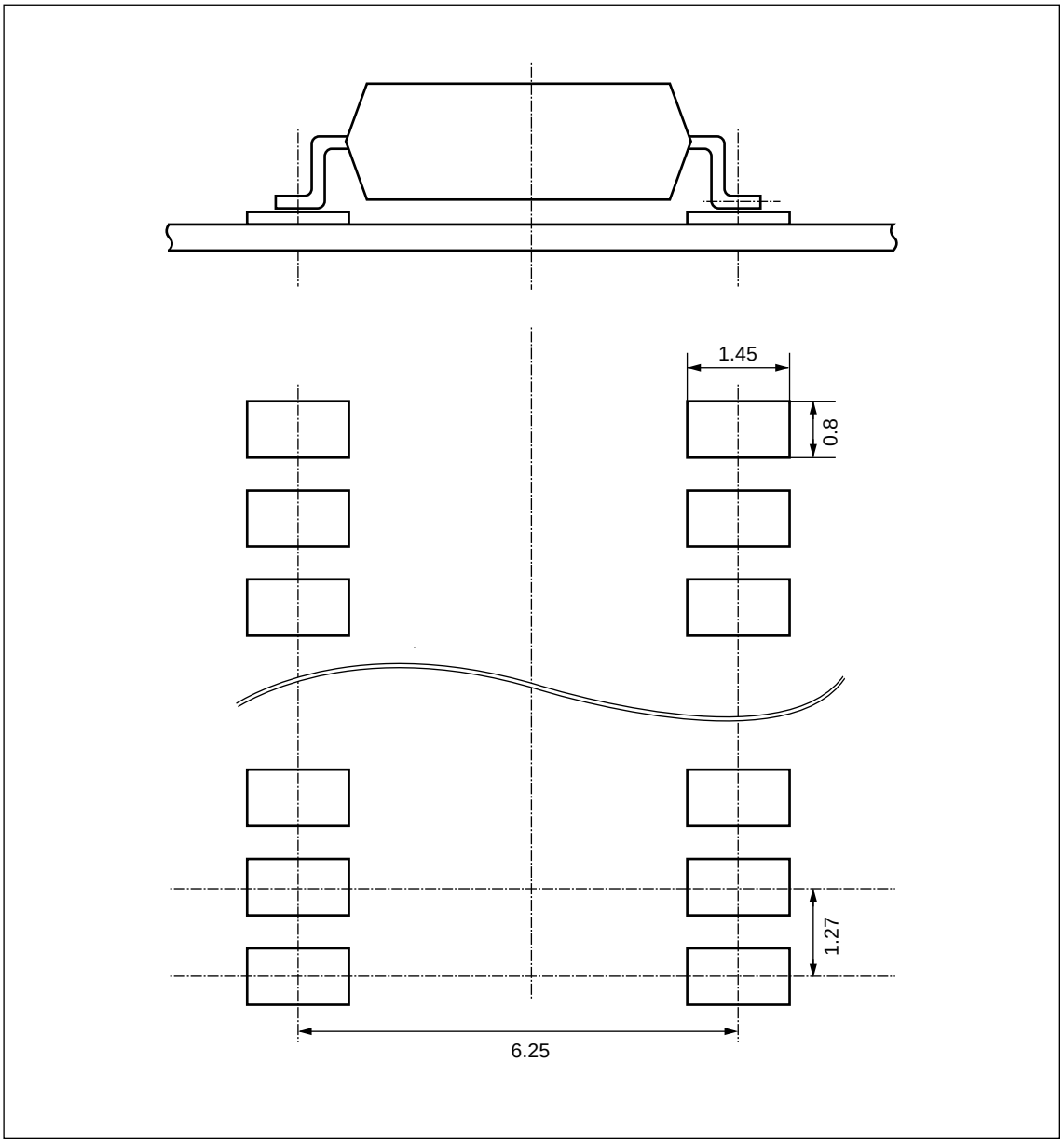


Outline and Dimensions (Reel)



Packing: 2 500 pcs/reel

RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



Remark All dimensions in this figure must be evaluated before use.

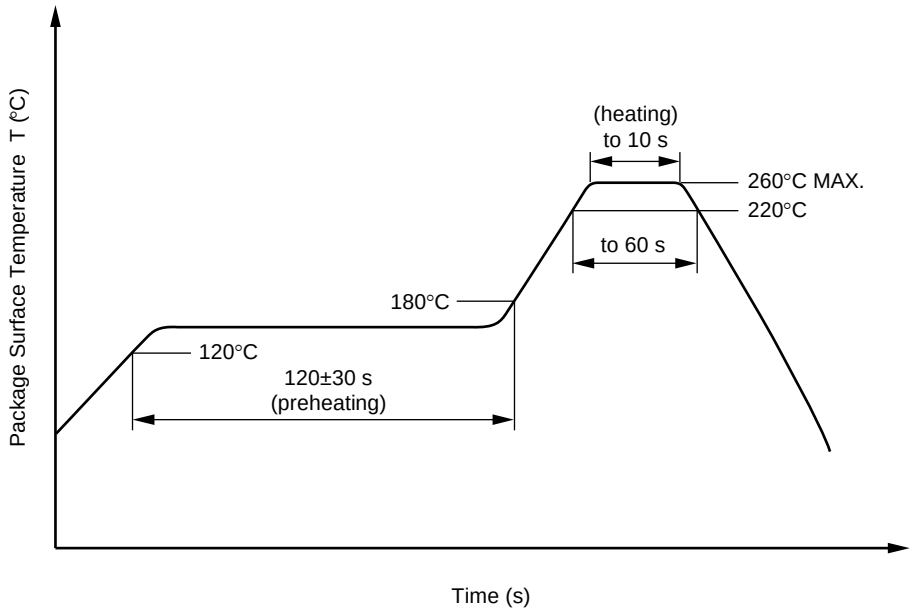
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

• Peak reflow temperature	260°C or below (package surface temperature)
• Time of peak reflow temperature	10 seconds or less
• Time of temperature higher than 220°C	60 seconds or less
• Time to preheat temperature from 120 to 180°C	120±30 s
• Number of reflows	Three
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

• Temperature	260°C or below (molten solder temperature)
• Time	10 seconds or less
• Preheating conditions	120°C or below (package surface temperature)
• Number of times	One (Allowed to be dipped in solder including plastic mold portion.)
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by Soldering Iron

• Peak Temperature (lead part temperature)	350°C or below
• Time (each pins)	3 seconds or less
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead

(4) Cautions

•Flux Cleaning

Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.

•Do not use fixing agents or coatings containing halogen-based substances.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. This tendency may sometimes be obvious, especially below I_F = 1 mA.

Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

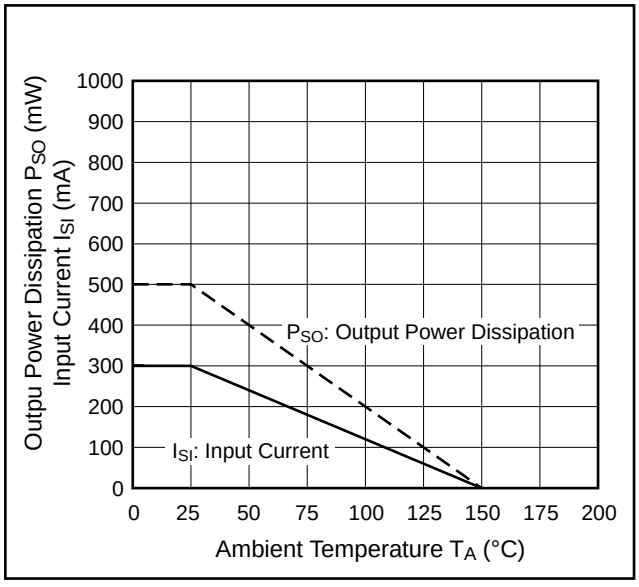
USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.
3. Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.
4. Do not use fixing agents or coatings containing halogen-based substances.

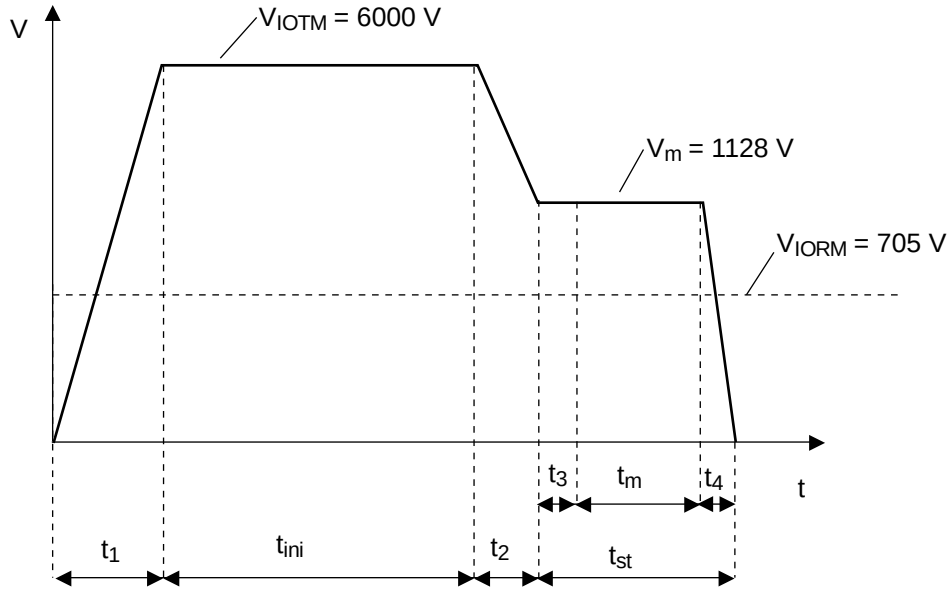
SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Rating	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		55/100/21	
Dielectric strength maximum operating isolation voltage Test voltage (partial discharge test, procedure a for type test and random test) $V_m = 1.6 \times V_{IORM.}$, $q_{pd} < 5$ pC	 V_{IORM} V_m	 705 1 128	 V_{peak} V_{peak}
Test voltage (partial discharge test, procedure b for all devices) $V_m = 1.875 \times V_{IORM.}$, $q_{pd} < 5$ pC	V_m	1 322	V_{peak}
Highest permissible overvoltage	V_{IOTM}	6 000	V_{peak}
Degree of pollution (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303-11))	CTI	175	
Material group (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))		III a	
Storage temperature range	T_{stg}	−55～+150	°C
Operating temperature range	T_A	−55～+100	°C
Isolation resistance, minimum value V_{I-O} = 500 V dc, T_A = 25 °C V_{I-O} = 500 V dc, T_A = maximum temperature of rating, at least 100 °C	 R_{I-O} MIN. R_{I-O} MIN.	 10^{12} 10^{11}	 Ω Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Maximum ambient temperature Maximum input current Maximum output power dissipation Isolation resistance, minimum value at V_{I-O} = 500 V dc, $T_A = T_S$	 T_S I_{SI} P_{SO} R_{I-O} MIN.	 150 300 500 10^9	 °C mA mW Ω

Dependence of maximum safety ratings with package temperature

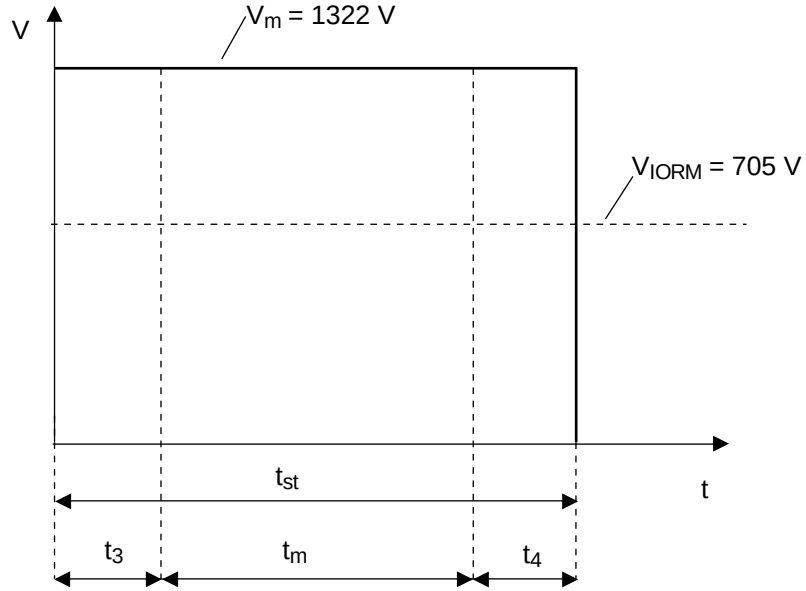


Method a) Destructive Test, Type and Sample Test



t_1, t_2 = 1 to 10 sec
t_3, t_4 = 1 sec
t_m = 10 sec
t_{st} = 12 sec
t_{ini} = 60 sec

Method b) Non-destructive Test, 100% Production Test



t_3, t_4 = 0.1 sec
t_m = 1.0 sec
t_{st} = 1.2 sec

Caution GaAs Products	This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points. • Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below. 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials. 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal. • Do not burn, destroy, cut, crush, or chemically dissolve the product. • Do not lick the product or in any way allow it to enter the mouth.

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